

## NCE N-Channel Enhancement Mode Power MOSFET

## Description

The NCE048N30Q uses advanced trench technology and design to provide excellent  $R_{DS(ON)}$  with low gate charge. It can be used in a wide variety of applications.

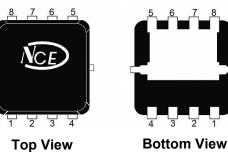
#### Application

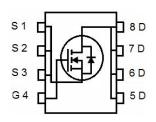
- Power switching application
- Hard Switched and High Frequency Circuits
- Uninterruptible Power Supply

#### **General Features**

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 V<sub>DS</sub> =30V,I<sub>D</sub> =45A R<sub>DS(ON)</sub>=4.2mΩ @ V<sub>GS</sub>=10V R<sub>DS(ON)</sub>=7.3mΩ @ V<sub>GS</sub>=4.5V
 High density cell design for ultra low Rdson
 Fully characterized Avalanche voltage and current
 Good stability and uniformity with high E<sub>AS</sub>
 Excellent package for good heat dissipation
 Special process technology for high ESD capability 100% UIS TESTED! 100% ΔVds TESTED!

PDFN 3.3X3.3-8L





Schematic Diagram

#### Package Marking and Ordering Information

Device Marking	Device	Device Package	Reel Size	Tape width	Quantity
NCE048N30Q	NCE048N30Q	PDFN3.3X3.3-8L	Ø330mm	12mm	5000 units

### Absolute Maximum Ratings (Tc=25°Cunless otherwise noted)

Parameter	Symbol	Limit	Unit	
Drain-Source Voltage	Vds	30	V	
Gate-Source Voltage	Vgs	±20	V	
Drain Current-Continuous	Ι <sub>D</sub>	45	А	
Drain Current-Continuous(Tc=100 ℃)	I <sub>D</sub> (100℃)	31.8	А	
Pulsed Drain Current	Ідм	180	А	
Maximum Power Dissipation	PD	38	W	
Derating factor		0.30	W/°C	
Single pulse avalanche energy <sup>(Note 1)</sup>	E <sub>AS</sub>	180	mJ	
Operating Junction and Storage Temperature Range	T <sub>J</sub> ,T <sub>STG</sub>	-55 To 150	°C	

#### **Thermal Characteristic**

Thermal Resistance, Junction-to-Case	Rejc	3.3	°C/W	
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## Electrical Characteristics (Tc=25°C unless otherwise noted)

Off Characteristics         Drain-Source Breakdown Voltage       BV <sub>DSS</sub> Zero Gate Voltage Drain Current       I <sub>DSS</sub> Gate-Body Leakage Current       I <sub>GSS</sub> On Characteristics       IGSS         Gate Threshold Voltage       V <sub>GS(th)</sub> Drain-Source On-State Resistance       R <sub>DS(ON)</sub> Forward Transconductance       gFS         Dynamic Characteristics       Input Capacitance         Output Capacitance       C <sub>Iss</sub>	$V_{GS}=0V I_{D}=250\mu A$ $V_{DS}=30V, V_{GS}=0V$ $V_{GS}=\pm 20V, V_{DS}=0V$ $V_{DS}=V_{GS}, I_{D}=250\mu A$	30 - -	-	-	V
Zero Gate Voltage Drain Current     IDSS       Gate-Body Leakage Current     IGSS       On Characteristics     IGSS       Gate Threshold Voltage     VGS(th)       Drain-Source On-State Resistance     RDS(ON)       Forward Transconductance     GFS       Dynamic Characteristics     Input Capacitance	$V_{DS}=30V, V_{GS}=0V$ $V_{GS}=\pm 20V, V_{DS}=0V$ $V_{DS}=V_{GS}, I_{D}=250\mu A$	-	-		V
Gate-Body Leakage Current     I <sub>GSS</sub> On Characteristics     Gate Threshold Voltage       VGS(th)     VGS(th)       Drain-Source On-State Resistance     RDS(ON)       Forward Transconductance     GFS       Dynamic Characteristics     Input Capacitance	V <sub>GS</sub> =±20V,V <sub>DS</sub> =0V V <sub>DS</sub> =V <sub>GS</sub> ,I <sub>D</sub> =250μA	-	-	1	t
On Characteristics       Gate Threshold Voltage     V <sub>GS(th)</sub> Drain-Source On-State Resistance     R <sub>DS(ON)</sub> Forward Transconductance     g <sub>FS</sub> Dynamic Characteristics     Input Capacitance	V <sub>DS</sub> =V <sub>GS</sub> ,I <sub>D</sub> =250µA	-	_	-	μA
Gate Threshold VoltageVGS(th)Drain-Source On-State ResistanceRDS(ON)Forward TransconductanceGFSDynamic CharacteristicsClass	· ·	·		±100	nA
Drain-Source On-State Resistance     RDS(ON)       Forward Transconductance     gFS       Dynamic Characteristics     Input Capacitance	· ·				
Forward Transconductance     g <sub>FS</sub> Dynamic Characteristics     Input Capacitance		1.0	1.6	2.5	V
Forward Transconductance     g <sub>FS</sub> Dynamic Characteristics     Input Capacitance	$V_{GS}$ =10V, $I_D$ =20A	-	4.2	4.8	mΩ
Dynamic Characteristics       Input Capacitance     Cliss	V <sub>GS</sub> =4.5V, I <sub>D</sub> =15A	-	7.3	9.5	mΩ
Input Capacitance C <sub>lss</sub>	V <sub>DS</sub> =5V,I <sub>D</sub> =20A	-	29	-	S
		·			
Output Capacitance Coss		-	1350	-	PF
	V <sub>DS</sub> =15V,V <sub>GS</sub> =0V,	-	220	-	PF
Reverse Transfer Capacitance C <sub>rss</sub>	F=1.0MHz	-	185	-	PF
Switching Characteristics (Note 2)					
Turn-on Delay Time t <sub>d(on)</sub>		-	6	-	nS
Turn-on Rise Time tr	V <sub>DD</sub> =15V, R <sub>L</sub> =0.75Ω	-	9	-	nS
Turn-Off Delay Time td(off)	V <sub>GS</sub> =10V,R <sub>G</sub> =3Ω	-	32	-	nS
Turn-Off Fall Time t <sub>f</sub>		-	8	-	nS
Total Gate Charge Qg	- V <sub>DS</sub> =15V,I <sub>D</sub> =20A,	-	31.3		nC
Gate-Source Charge Qgs		-	3.7		nC
Gate-Drain Charge Qgd	V <sub>GS</sub> =10V	-	8		nC
Drain-Source Diode Characteristics			<u>.</u>		
Diode Forward Voltage V <sub>SD</sub>	V <sub>GS</sub> =0V,I <sub>S</sub> =20A	-		1.2	V
Diode Forward Current Is		-	-	45	Α
Reverse Recovery Time t <sub>rr</sub>	TJ = 25°C, IF =20A	-	45	-	nS
Reverse Recovery Charge Qrr			1		
Forward Turn-On Time t <sub>on</sub>	di/dt = 100A/µs	-	22	-	nC

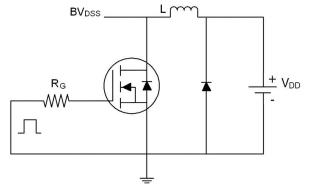
#### Notes:

- 1. EAS condition : Tj=25  $^\circ \!\! \mathbb{C}$  ,V\_DD=30V,V\_G=10V,L=0.5mH,Rg=25 $\Omega$
- 2. Guaranteed by design, not subject to production
- 3. These curves are based on the junction-to-case thermal impedance which is measured with the device mounted to a large heatsink, assuming a maximum junction temperature of T<sub>J(MAX)</sub>=150°C. The SOA curve provides a single pulse rating.

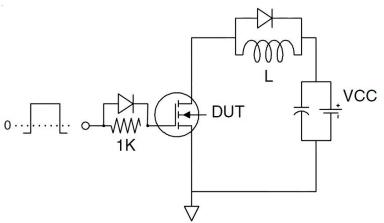


## **Test circuit**

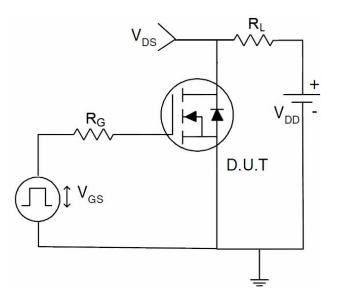
## 1) E<sub>AS</sub> test Circuits



2) Gate charge test Circuit:

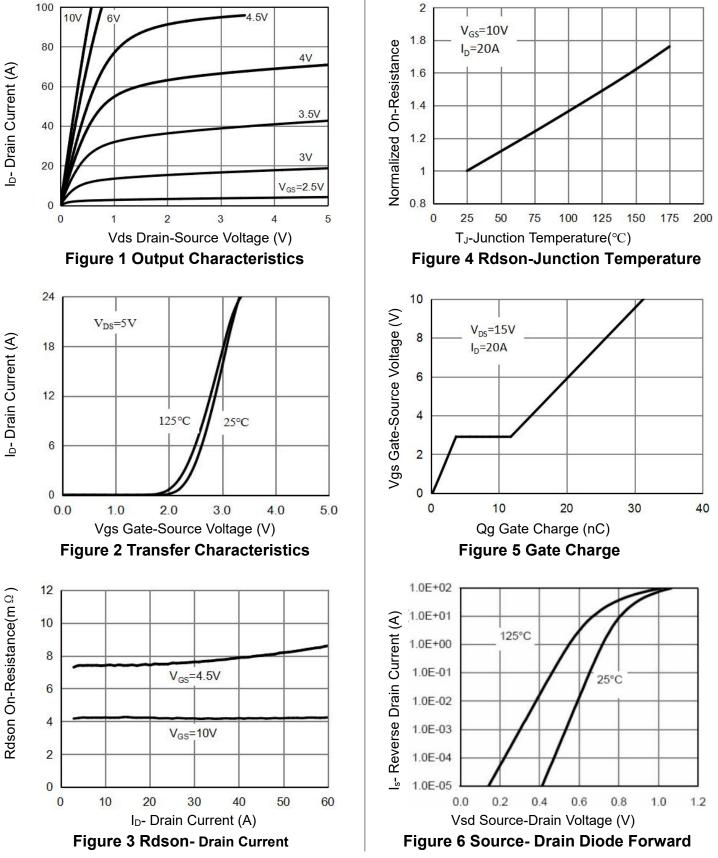


3) Switch Time Test Circuit:





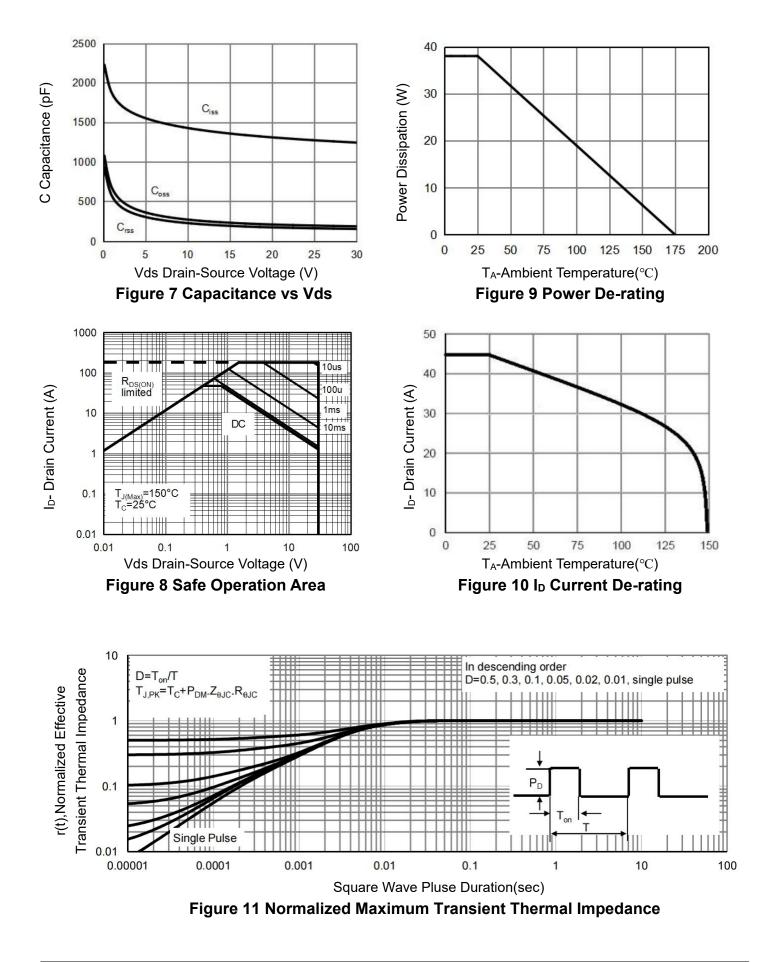






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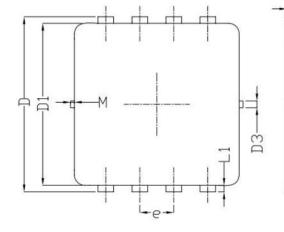
# NCE048N30Q

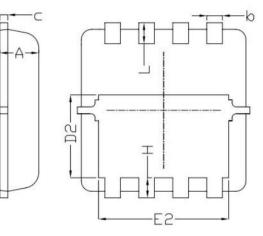


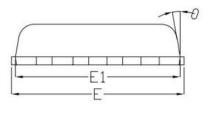


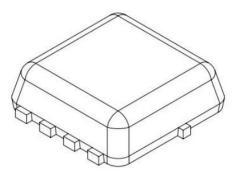
# NCE048N30Q

## PDFN3.3X3.3-8L Package Information



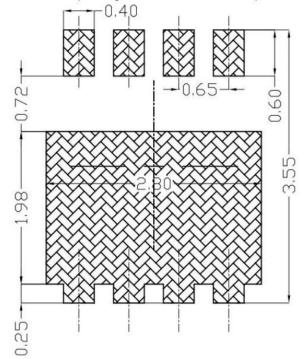






Land Pattern (Only for Reference)

ava (bot	DIMENSIONAL REQMTS			
SYMBOL	MIN	NOM	MAX	
A	0.70	0.75	0.80	
b	0.25	0.30	0.35	
С	0.10	0.15	0.25	
D	3.25	3.35	3.45	
D1	3.00	3.10	3.20	
D2	1.48	1.58	1.68	
D3		0.13		
E	3.20	3.30	3.40	
E1	3.00	3.15	3.20	
E2	2.39	2.49	2.59	
е	0.65BSC			
H	0.30	0.39	0.50	
L	0.30	0.40	0.50	
LI		0.13		
$\theta$		10°	12°	
М	*	*	0.15	





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